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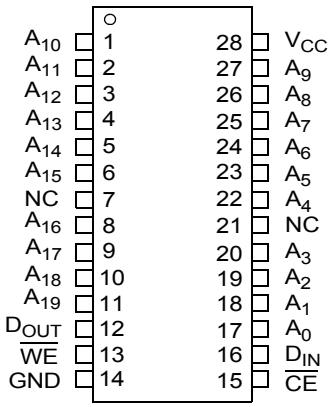
Pin Configuration

Figure 1. 28-pin SOJ pinout (Top View) [2]



Selection Guide

Description	CY7C107D-10 CY7C1007D-10	Unit
Maximum access time	10	ns
Maximum operating current	80	mA
Maximum CMOS standby current, I_{SB2}	3	mA

Note
2. NC pins are not connected on the die.

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature ..... –65 °C to +150 °C

Ambient temperature with power applied ..... –55 °C to +125 °C

Supply voltage on V_{CC} relative to GND [3] ..... –0.5 V to +6.0 V

DC voltage applied to outputs in High-Z state [3] ..... –0.5 V to V_{CC} + 0.5 V

DC input voltage [3] ..... –0.5 V to V_{CC} + 0.5 V

Current into outputs (LOW) ..... 20 mA

Static discharge voltage (per MIL-STD-883, Method 3015) ..... > 2001 V

Latch-up current ..... > 200 mA

Operating Range

Range	Ambient Temperature	V_{CC}	Speed
Industrial	–40 °C to +85 °C	5 V ± 0.5 V	10 ns

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions		7C107D-10 7C1007D-10 Min	7C107D-10 7C1007D-10 Max	Unit
V_{OH}	Output HIGH voltage	I_{OH} = –4.0 mA		2.4	–	V
		I_{OH} = –0.1 mA		–	3.4 [4]	
V_{OL}	Output LOW voltage	I_{OL} = 8.0 mA		–	0.4	V
V_{IH}	Input HIGH voltage			2.2	V_{CC} + 0.5	V
V_{IL}	Input LOW voltage [3]			–0.5	0.8	V
I_{IX}	Input leakage current	GND ≤ V_I ≤ V_{CC}		–1	+1	µA
I_{OZ}	Output leakage current	GND ≤ V_I ≤ V_{CC}, output disabled		–1	+1	µA
I_{CC}	V_{CC} operating supply current	V_{CC} = Max, I_{OUT} = 0 mA, f = f_{max} = $1/t_{RC}$	100 MHz	–	80	mA
			83 MHz	–	72	mA
			66 MHz	–	58	mA
			40 MHz	–	37	mA
I_{SB1}	Automatic $\overline{CE}$ Power-down current – TTL Inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{max}		–	10	mA
I_{SB2}	Automatic $\overline{CE}$ Power-down current – CMOS Inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V, V_{IN} ≥ V_{CC} – 0.3V or V_{IN} ≤ 0.3V, f = 0		–	3	mA

Note

3. V_{IL} (min) = –2.0 V and V_{IH}(max) = V_{CC} + 1 V for pulse durations of less than 5 ns.
4. Please note that the maximum V_{OH} limit does not exceed minimum CMOS VIH of 3.5V. If you are interfacing this SRAM with 5 V legacy processors that require a minimum V_{IH} of 3.5 V, please refer to Application Note AN6081 for technical details and options you may consider.

Capacitance

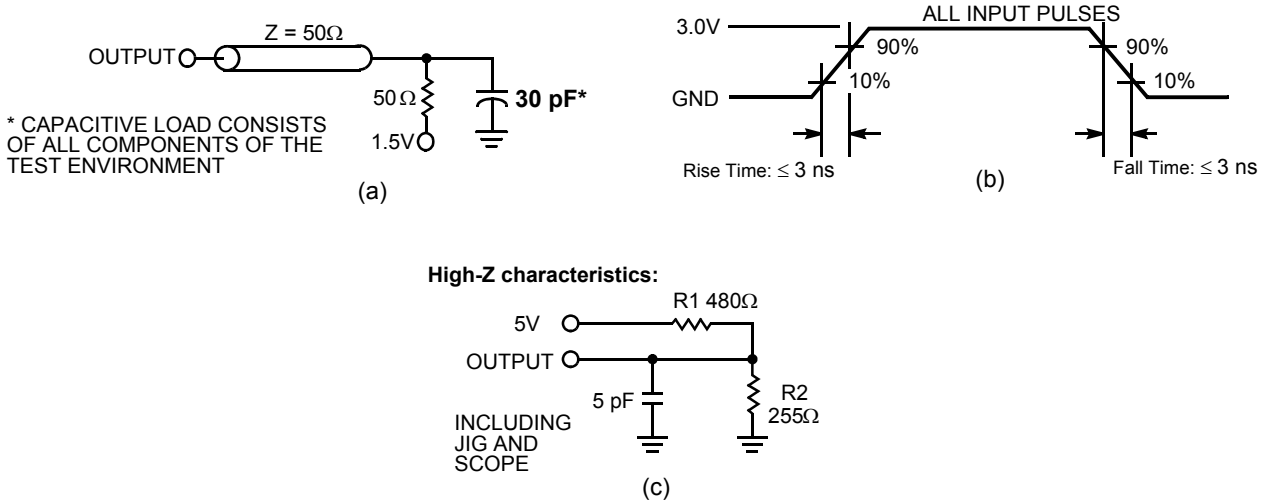
Parameter [5]	Description	Test Conditions	Max	Unit
C_{IN}: Addresses	Input capacitance	T_A = 25 °C, f = 1 MHz, V_{CC} = 5.0 V	7	pF
C_{IN}: Controls			10	pF
C_{OUT}	Output capacitance		10	pF

Thermal Resistance

Parameter [5]	Description	Test Conditions	300-Mil Wide SOJ	400-Mil Wide SOJ	Unit
Θ_{JA}	Thermal resistance (junction to ambient)	Still Air, soldered on a 3 × 4.5 inch, four-layer printed circuit board	59.16	58.76	°C/W
Θ_{JC}	Thermal resistance (junction to case)		40.84	40.54	°C/W

AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms [6]



Notes
5. Tested initially and after any design or process changes that may affect these parameters.
6. AC characteristics (except High-Z) are tested using the load conditions shown in Figure 2 (a). High-Z characteristics are tested for all speeds using the test load shown in Figure 2 (c).

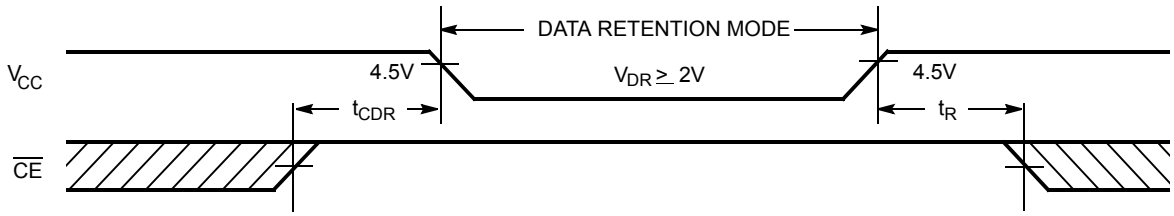
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Max	Unit
V_{DR}	V_{CC} for data retention		2.0	–	V
I_{CCDR}	Data retention current	$V_{CC} = V_{DR} = 2.0$ V, $\overline{CE} \geq V_{CC} - 0.3$ V, $V_{IN} \geq V_{CC} - 0.3$ V or $V_{IN} \leq 0.3$ V	–	3	mA
t_{CDR} [7]	Chip deselect to data retention time		0	–	ns
t_R [8]	Operation recovery time		t_{RC}	–	ns

Data Retention Waveform

Figure 3. Data Retention Waveform



Notes

7. AC characteristics (except High-Z) are tested using the load conditions shown in Figure 2 (a). High-Z characteristics are tested for all speeds using the test load shown in Figure 2 (c).
8. Full device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min)} \geq 50$ µs or stable at $V_{CC(min)} \geq 50$ µs.

Switching Characteristics

Over the Operating Range

Parameter [9]	Description	7C107D-10 7C1007D-10		Unit
		Min	Max	
Read Cycle				
t_{power} [10]	V_{CC}(typical) to the first access	100	–	µs
t_{RC}	Read cycle time	10	–	ns
t_{AA}	Address to data valid	–	10	ns
t_{OHA}	Data hold from address change	3		ns
t_{ACE}	$\overline{CE}$ LOW to data valid	–	10	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z [11]	3	–	ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z [11, 12]	–	5	ns
t_{PU} [13]	$\overline{CE}$ LOW to power-up	0	–	ns
t_{PD} [13]	$\overline{CE}$ HIGH to power-down	–	10	ns
Write Cycle [14]				
t_{WC}	Write cycle time	10	–	ns
t_{SCE}	$\overline{CE}$ LOW to write end	7	–	ns
t_{AW}	Address set-up to write end	7	–	ns
t_{HA}	Address hold from write end	0	–	ns
t_{SA}	Address set-up to write start	0	–	ns
t_{PWE}	$\overline{WE}$ pulse width	7	–	ns
t_{SD}	Data set-up to write end	6	–	ns
t_{HD}	Data hold from write end	0	–	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z [11]	3	–	ns
t_{HZWE}	$\overline{WE}$ LOW to High Z [11, 12]	–	6	ns

Notes

9. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
10. t_{POWER} gives the minimum amount of time that the power supply should be at typical V_{CC} values until the first memory access can be performed.
11. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} and t_{HZWE} is less than t_{LZWE} for any given device.
12. t_{HZCE} and t_{HZWE} are specified with a load capacitance of 5 pF as in part (c) of Figure 2 on page 5. Transition is measured when the outputs enter a high impedance state.
13. This parameter is guaranteed by design and is not tested.
14. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. $\overline{CE}$ and $\overline{WE}$ must be LOW to initiate a write, and the transition of any of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.

Switching Waveforms

Figure 4. Read Cycle No. 1 (Address Transition Controlled) [15, 16]

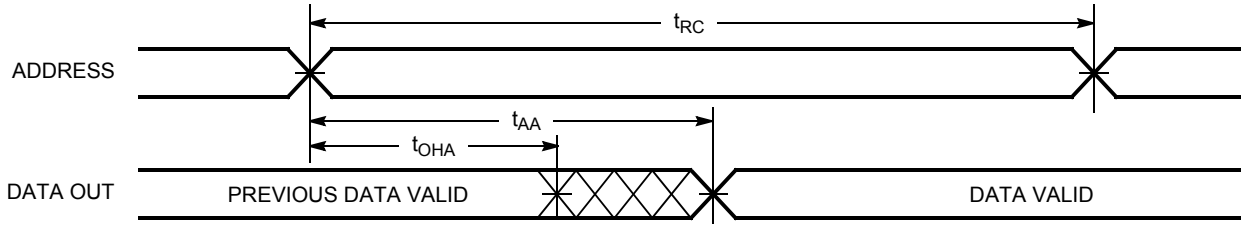
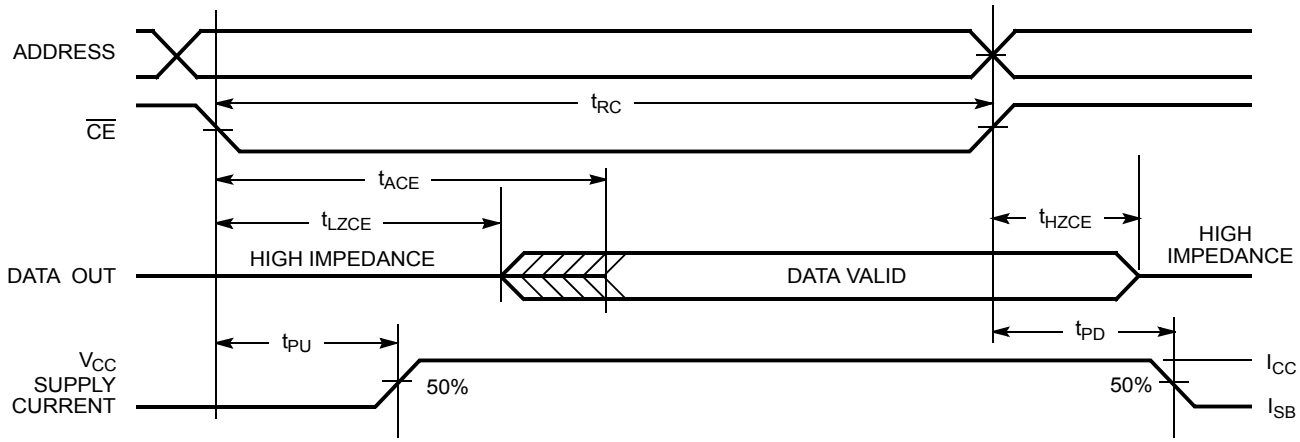


Figure 5. Read Cycle No. 2 [16, 17]



Notes

15. Device is continuously selected, $\overline{CE} = V_{IL}$.
16. $\overline{WE}$ is HIGH for read cycle.
17. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms(continued)

Figure 6. Write Cycle No. 1 ($\overline{CE}$ Controlled) [18]

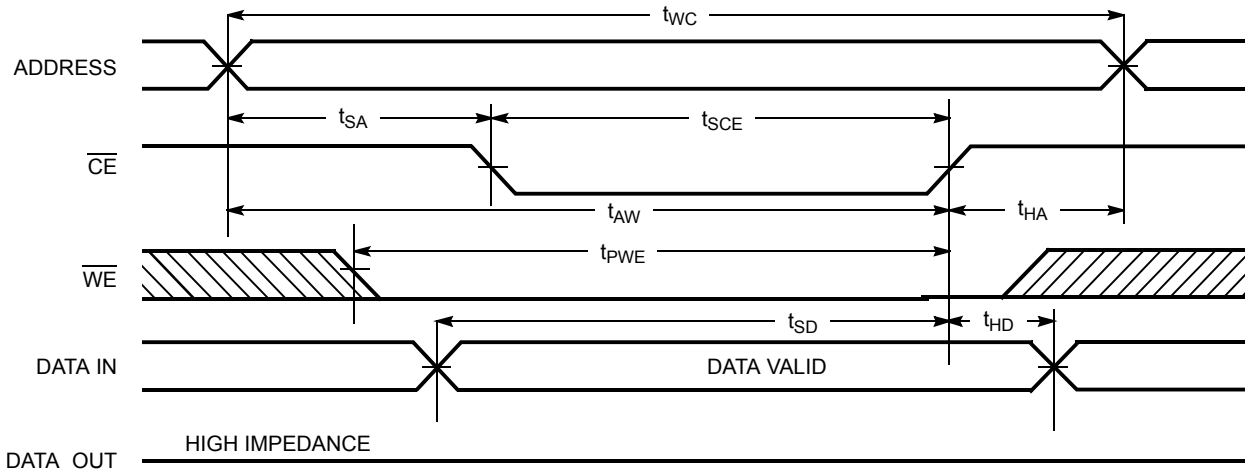
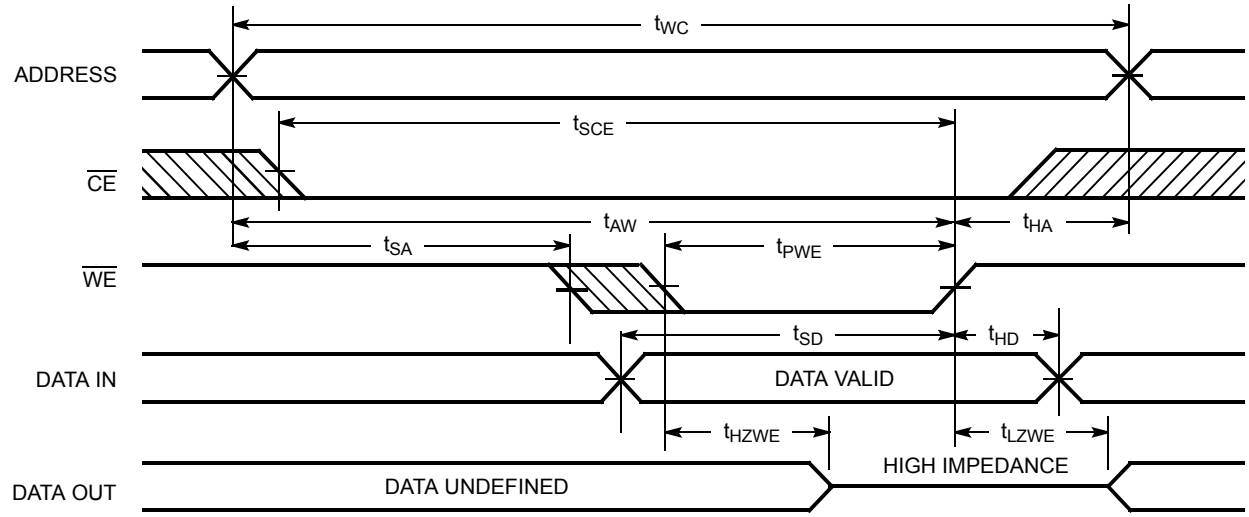


Figure 7. Write Cycle No. 2 ($\overline{WE}$ Controlled) [18]



Note
18. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ going HIGH, the output remains in a high-impedance state.

Truth Table

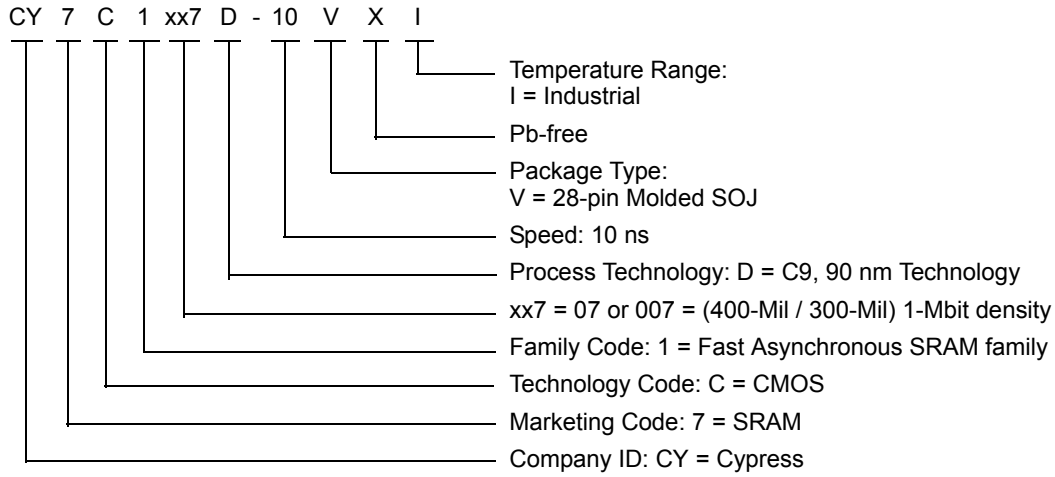
$\overline{CE}$	$\overline{WE}$	D_{OUT}	Mode	Power
H	X	High Z	Power-down	Standby (I_{SB})
L	H	Data out	Read	Active (I_{CC})
L	L	High Z	Write	Active (I_{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
10	CY7C107D-10VXI	51-85032	28-pin (400-Mil) Molded SOJ (Pb-free)	Industrial
	CY7C1007D-10VXI	51-85031	28-pin (300-Mil) Molded SOJ (Pb-free)	

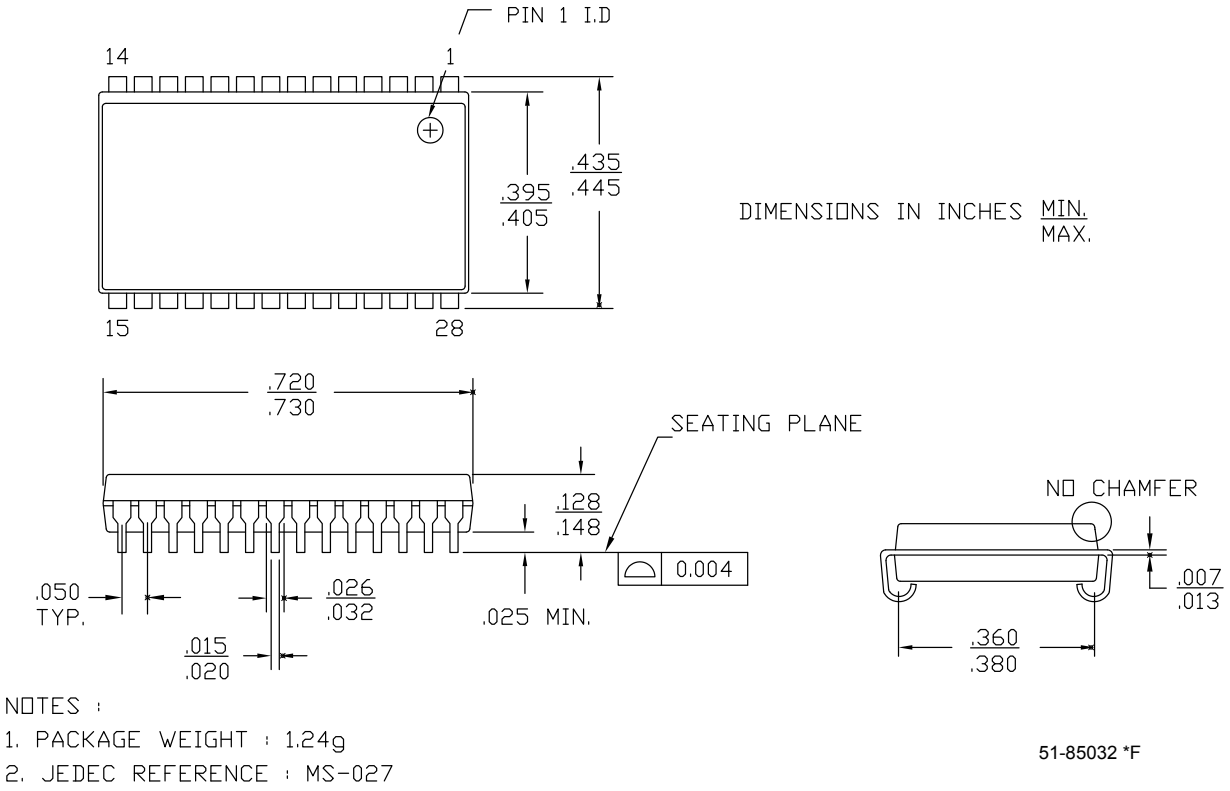
Please contact your local Cypress sales representative for availability of these parts.

Ordering Code Definitions



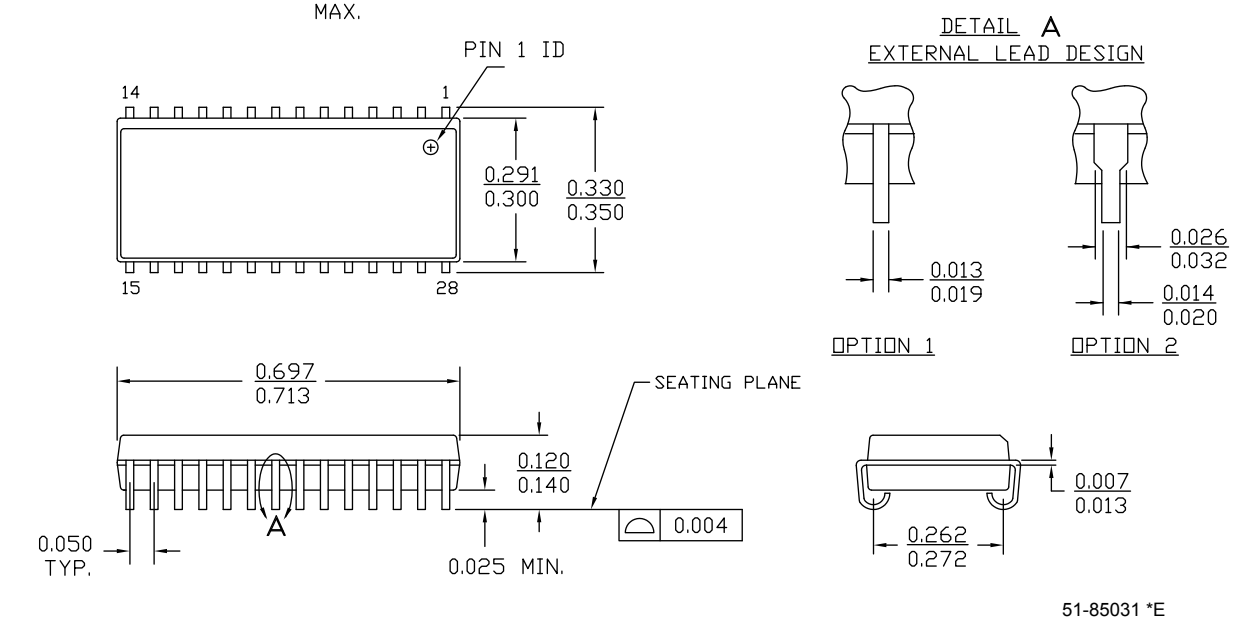
Package Diagrams

Figure 8. 28-pin SOJ (400 Mils) V28.4 (Molded SOJ V28) Package Outline, 51-85032



Package Diagrams(continued)

Figure 9. 28-pin SOJ (300 Mils) V28.3 (Molded SOJ V21) Package Outline, 51-85031



Acronyms

Acronym	Description
BGA	Ball Grid Array
$\overline{BHE}$	Byte High Enable
$\overline{BLE}$	Byte Low Enable
$\overline{CE}$	Chip Enable
CMOS	Complementary Metal Oxide Semiconductor
FBGA	Very Fine-Pitch Ball Grid Array
I/O	Input/Output
JTAG	Joint Test Action Group
SRAM	Static Random Access Memory
TTL	Transistor-Transistor Logic
$\overline{WE}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
MHz	megahertz
µA	microampere
mA	milliampere
ns	nanosecond
Ω	ohm
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C107D/CY7C1007D, 1-Mbit (1 M × 1) Static RAM Document Number: 38-05469				
Rev.	**ECN No.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	201560	See ECN	SWI	Advance Information data sheet for C9 IPP
*A	233722	See ECN	RKF	DC parameters modified as per EROS (Spec # 01-02165) Pb-free offering in Ordering Information
*B	263769	See ECN	RKF	Added Data Retention Characteristics table Added T_{power} Spec in Switching Characteristics Table Shaded Ordering Information
*C	307601	See ECN	RKF	Reduced Speed bins to –10 and –12 ns
*D	560995	See ECN	VKN	Converted from Preliminary to Final Removed Commercial Operating range Removed 12 ns speed bin Added I_{CC} values for the frequencies 83MHz, 66MHz and 40MHz Updated Thermal Resistance table Updated Ordering Information Table Changed Overshoot spec from V_{CC}+2V to V_{CC}+1V in footnote #3
*E	802877	See ECN	VKN	Changed I_{CC} specs from 60 mA to 80 mA for 100MHz, 55 mA to 72 mA for 83MHz, 45 mA to 58 mA for 66MHz, 30 mA to 37 mA for 40MHz
*F	2898399	03/24/2010	AJU	Updated Package Diagrams
*G	3104943	12/08/2010	AJU	Added Ordering Code Definitions.
*H	3218989	04/07/2011	PRAS	Added TOC Added Acronyms and Units of Measure table. Updated Package diagrams from *C to *D (51-85032)
*I	4040950	06/26/2013	MEMJ	Updated Functional Description. Updated Electrical Characteristics Added one more Test Condition "I_{OH} = –0.1mA" for V_{OH} parameter and added maximum value corresponding to that Test Condition. Added Note 4 and referred the same note in maximum value for V_{OH} parameter corresponding to Test Condition "I_{OH} = –0.1mA". Updated Package Diagrams: spec 51-85031 – Changed revision from *D to *E. Updated in new template.
*J	4385003	05/23/2014	MEMJ	Updated Package Diagrams: spec 51-85032 – Changed revision from *E to *F. Completing Sunset Review.
*K	4578500	11/24/2014	MEMJ	Added related documentation hyperlink in page 1.

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